FORM PTO-1595	RECOR	09-13	-2002	U.S. DEPARTMENT OF COMMERCE
(Rev. 6-93) OMB No. 0651-0011 (exp. 4/94)				Patent and Trademark Office
To the Honorable Co	ommissioner of Paten.	10222	20712 <u>1</u>	original documents or copy thereof
1. Name of conveying party(ies):		2. Name and address	of receiving party(ies):
Seong-Jin Jang Jin-Seok Kwak	9-5-02		Name: Samsung	Electronics, Co., Ltd.
			Internal Address:	Tr Tr
Additional name(s) of conveying pa	rty(ies) attached?	es 🖾 No		
3. Nature of conveyance:			Street Address:	416, Maetan-dong, Paldal-gu,
	□ Me	ger	Suwon-city, Kyı	ingki-do, Republic of Korea
☐ Security Agreemen	ıt □ Cha	nge of Name	City:	State ZIP
☐ Other		inge of realise		
	igust 30, 2002		Additional #ame(s) & addr	ess attached? □ Yes ⊠ No
4. Application number(s) or p			10/235/	OU TOS LA TAY
If this document is being filed together with a new application, the execution date of the application				On is: August 30, 2002
A. Patent Application No.(s)			B. Patent No.(s)	
			,	
	Additional m	umbers attached	? □ Yes 🛛 No	
				plications and registrations
5. Name and address of party document should be mailed:	to whom correspondence of	involved		
Name: Anthony P. Or	nello, Jr.			740.00
Internal Address: MI	LLS & ONELLO LLP		7. Total fee (37 CFR :	\$40.00
incinal reduces.	EES & OTTERES EET			
			☐ Authorized to be	charged to deposit account
Street Address: Ele	even Beacon Street, Suite 6	05	8. Deposit Account N	umber:
City: Boston	State MA Z	IP <u>02108</u>	(Attach duplicate copy of the	nis page if paying by deposit account)
	D	O NOT USE T	THIS SPACE	
9. Statement and signature: To the best of my knowledge document.	and belief, the foregoing in	formation is tru	e and correct and any at	tached copy is a true copy of the original
Anthony P. Onello, Jr.	Reg. No. 38 572	Chitti	au 22111	Section 5 2002
Name of Person Signi		Signature	- me	Date
•	imber of pages including co		nments, and document	3
09/12/2002 LINUELLER 00000262			_	· · · · · · · · · · · · · · · · · · ·
D1 FC:581	Mail documents to be r	ecorded with r	equired cover sheet info	ormation to:

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Washington, D.C. 20231

Reference No.: SAM-0359

ASSIGNMENT

We, Scong-Jin Jang, of Kumkang Apt., 104-704, Emae-dong, 122, Bundang-gu, SungnamBcity, Kyunggi-do, 463-796, Republic of Korea; and Jin-Seok Kwak, of Jugong Apt., 915-505, Bucjukgol, 970-3, Youngtong-dong, Paldal-gu, Suwon-city, Kyunggi-do, 442-726, Republic of Korea; having invented improvements in CIRCUIT AND METHOD FOR CONTROLLING ON-DIE SIGNAL TERMINATION described in an application for Letters Patent of the United States, executed by us on even date herewith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignce, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignce, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignce, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

Page 1 of 2

Reference No.: SAM-0359

First or Sole Inventor:

Signature

Seong Jin Jang
Seong-Jin Jang

Date: 3.14, Ang. 2002

Second Joint Inventor:

Signature:

RECORDED: 09/05/2002

Jin-Seok Kwak

Date: 30th, Aug. 2002

REFERENCE NO.: SAM-0359
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